- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

The '279 offers 4 basic $\overline{S} \cdot \overline{R}$ flip-flop latches in one 16-pin, 300-mil package. Under conventional operation, the $\overline{S} \cdot \overline{R}$ inputs are normally held high. When the \overline{S} input is pulsed low, the Ω output will be set high. When \overline{R} is pulsed low, the Ω output will be reset low. Normally, the $\overline{S} \cdot \overline{R}$ inputs should not be taken low simultaneously. The Ω output will be unpredictable in this condition.

FUNCTION TABLE (each latch)

INP	UTS	OUTPUT
St	R	a
н	Н	α ₀
L	Н	н
н	L	L
L	L	Н‡

H = high level

L = low level

†For latches with double S inputs:

 Ω_0 = the level of Ω before the indicated input conditions were established.

 ‡ This configuration is nonstable: that is, it may not persist when the \overline{S} and \overline{R} inputs return to their inactive (high) level.

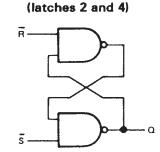
 $H = both \overline{S}$ inputs high

L = one or both \$\overline{S}\$ inputs low

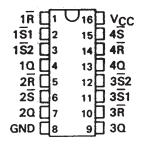
logic diagram (positive logic)

R C

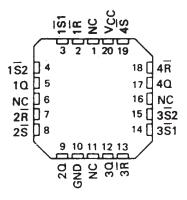
(latches 1 and 3)



SN54279, SN54LS279A . . . J OR W PACKAGE SN74279 . . . N PACKAGE SN74LS279A . . . D OR N PACKAGE (TOP VIEW)

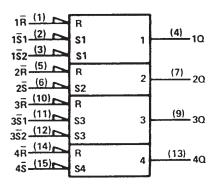


SN54LS279A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

logic symbol§



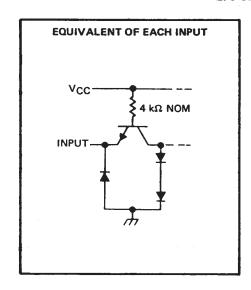
§This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

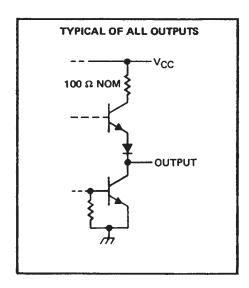
Pin numbers shown are for D, J, N, and W packages.

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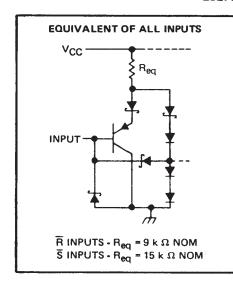
schematics of inputs and outputs

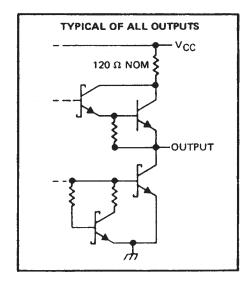
'279 CIRCUITS





'LS279A CIRCUITS





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	7 V
Input voltage: '279	5.5 V
' LS279A	7 V
Operating free-air temperature range: SN54' TYPES	55° C to 125° C
SN74' TYPES	0° C to 70° C
Storage temperature range	65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



recommended operating conditions

			SN54279			SN74279			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
VCC	Supply voltage	4.5	5	5.5	4.75	5	5.25	V	
VIH	High-level input voltage	2			2			V	
VIL	Low-level input voltage			0.8		-	0.8	V	
ЮН	High-level output current			- 0.8			- 0.8	mA	
IOL	Low-level output current			16			16	mA	
t _W	Pulse duration, low	20			20			ns	
TA	Operating free-air temperature	- 55		125	0	-	70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		noue†		SN5427	9		SN7427	9	UNIT	
FANAME (Ch		TEST CONDITIONS T				MAX	MIN	TYP‡	MAX	UNII
VIK	VCC = MIN,	I _I = - 12 mA				– 1.5			- 1.5	V
Voн	V _{CC} = MIN,	V _{IL} = 0.8 V,	1 _{OH} = - 0.8 mA	2.4	3.4		2.4	3.4		V
VOL	V _{CC} = MIN,	V _{1H} = 2 V,	1 _{OL} = 16 mA		0.2	0.4		0.2	0.4	V
11	V _{CC} = MAX,	V _I = 5.5 V				1			1	mA
Чн	V _{CC} = MAX,	V ₁ = 2.4 V				40			40	μΑ
IIL	V _{CC} = MAX,	V ₁ = 0.4 V				- 1.6			- 1.6	mA
I _{OS} \$	V _{CC} = MAX			- 18		- 55	- 18		- 57	mA
1cc	V _{CC} = MAX,	See Note 2			18	30		18	30	mΑ

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: I_{CC} is measured with all R inputs grounded, all S inputs at 4.5 V, and all outputs open.

switching characteristics, VCC = 5 V, TA = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	IDITIONS	MIN	TYP	MAX	UNIT
^t PLH	<u>-</u>					12	22	ns
^t PHL	3		$R_L = 400 \Omega$,	C ₁ = 15 pF		9	15	113
^t PHL	Ř	Q				15	27	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

^{\$} All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ} \text{C}$.

Not more than one output should be shorted at a time.

SN54279, SN54LS279A, SN74279, SN74LS279A QUADRUPLE \overline{S} - \overline{R} LATCHES

SDLS093 - DECEMBER 1983 - REVISED MARCH 1988

recommended operating conditions

		SN	SN54LS279A			SN74LS279A			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	٧	
VIH	High-level input voltage	2			2			V	
VIL	Low-level input voltage			0.7			0.8	٧	
ТОН	High-level output current			0.4			- 0.4	mA	
loL	Low-level output current			4			8	mA	
t _W	Pulse duration, low	20			20			ns	
TA	Operating free-air temperature	– 55		125	0		70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS†			Si	154LS27	79A	SN	174LS27	79A	UNIT
PARAMETER		1521 CONDIT	IUNS	MIN	TYP#	MAX	MIN	TYP‡	MAX	UNIT
VIK	V _{CC} = MIN,	I _I = - 18 mA				1.5			- 1.5	V
Voн	V _{CC} = MIN,	VIL = MAX,	I _{OH} = 0.4 mA	2.5	3.4		2.7	3.4	-	V
V	V _{CC} = MIN,	V _{IH} = 2 V,	IOL = 4 mA		0.25	0.4		0.25	0.4	V
VOL	V _{CC} = MIN,	V _{1H} = 2 V,	IOL = 8 mA					0.25	0.5	v
11	V _{CC} = MAX,	V ₁ = 7 V				0.1			0.1	mA
Чн	V _{CC} = MAX,	V ₁ = 2.7 V				20			20	μΑ
I _Ι Γ	V _{CC} = MAX,	V ₁ = 0.4 V				- 0.2			- 0.2	mA
IOS §	V _{CC} = MAX			- 20		- 100	- 20		- 100	mA
¹cc	V _{CC} = MAX,	See note 2			3.8	7		3.8	7	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: I_{CC} is measured with all R inputs grounded, all S inputs at 4.5 V, and all outputs open.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST COM	MIN	ТҮР	MAX	UNIT	
tPLH	_	0				12	22	ns
tPHL	3	4	$R_L = 2 k\Omega$,	C _L = 15 pF		13	21	113
[†] PHL	Ā	Q				15	27	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ} \text{C}$.

[§] Not more than one output should be shorted at a time, and the duration of the short-circuit should be less than one second.

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
76018012A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	76018012A SNJ54LS 279AFK
7601801EA	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	7601801EA SNJ54LS279AJ
7601801EA	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	7601801EA SNJ54LS279AJ
7601801FA	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	7601801FA SNJ54LS279AW
7601801FA	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	7601801FA SNJ54LS279AW
SN54LS279AJ	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54LS279AJ
SN54LS279AJ	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54LS279AJ
SN54LS279AJ.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54LS279AJ
SN54LS279AJ.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54LS279AJ
SN74LS279AD	Obsolete	Production	SOIC (D) 16	-	-	Call TI	Call TI	0 to 70	LS279A
SN74LS279AD	Obsolete	Production	SOIC (D) 16	-	-	Call TI	Call TI	0 to 70	LS279A
SN74LS279ADR	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS279A
SN74LS279ADR	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS279A
SN74LS279ADR.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS279A
SN74LS279ADR.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS279A
SN74LS279AN	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS279AN
SN74LS279AN	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS279AN
SN74LS279AN.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS279AN
SN74LS279AN.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS279AN
SN74LS279ANE4	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS279AN
SN74LS279ANE4	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS279AN
SN74LS279ANSR	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS279A
SN74LS279ANSR	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS279A
SN74LS279ANSR.A	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS279A
SN74LS279ANSR.A	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS279A





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Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
SNJ54LS279AFK	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	76018012A SNJ54LS 279AFK
SNJ54LS279AFK	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	76018012A SNJ54LS 279AFK
SNJ54LS279AFK.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	76018012A SNJ54LS 279AFK
SNJ54LS279AFK.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	76018012A SNJ54LS 279AFK
SNJ54LS279AJ	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	7601801EA SNJ54LS279AJ
SNJ54LS279AJ	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	7601801EA SNJ54LS279AJ
SNJ54LS279AJ.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	7601801EA SNJ54LS279AJ
SNJ54LS279AJ.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	7601801EA SNJ54LS279AJ
SNJ54LS279AW	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	7601801FA SNJ54LS279AW
SNJ54LS279AW	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	7601801FA SNJ54LS279AW
SNJ54LS279AW.A	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	7601801FA SNJ54LS279AW
SNJ54LS279AW.A	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	7601801FA SNJ54LS279AW

⁽¹⁾ Status: For more details on status, see our product life cycle.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

PACKAGE OPTION ADDENDUM

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(4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF SN54LS279A, SN74LS279A:

Catalog: SN74LS279A

Military: SN54LS279A

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

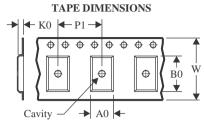
Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS279ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS279ANSR	SOP	NS	16	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS279ADR	SOIC	D	16	2500	340.5	336.1	32.0
SN74LS279ANSR	SOP	NS	16	2000	353.0	353.0	32.0

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
76018012A	FK	LCCC	20	55	506.98	12.06	2030	NA
7601801FA	W	CFP	16	25	506.98	26.16	6220	NA
SN74LS279AN	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS279AN	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS279AN.A	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS279AN.A	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS279ANE4	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS279ANE4	N	PDIP	16	25	506	13.97	11230	4.32
SNJ54LS279AFK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54LS279AFK.A	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54LS279AW	W	CFP	16	25	506.98	26.16	6220	NA
SNJ54LS279AW.A	W	CFP	16	25	506.98	26.16	6220	NA

D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP2-F16



8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



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14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOP



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



SOF



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOF



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



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